ZZI Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.

ZZ2 ■ These assemblies are ESD sensitive, ESD precautions shall be observed

ZZ3 These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4 ■ These assembles must comply with workmanship standards IPC-A-610 Class 2., unless otherwise specified.

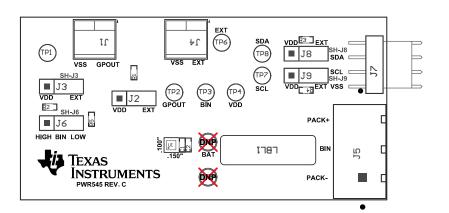


TABLE 1					
Variant	Label text				
001	bq27621EVM-G1				
002	NA				

TABLE 4

## COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED, AND MAY NOT BE IN BILL OF MATERIALS ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: PW	R545	REV: C	SVN REV:	Not In VersionControl
IGNORE -> Top Overlay					
PLOT NAME = Top Assembly Draw	ing GENERATED	: 2/20/2014	4 3: 28:12	⊃M	TEXAS INSTRUMENTS

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